



**ELECTRONICS, INC.**  
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## NTE5332 & NTE5334 Silicon Bridge Rectifier, 1A

**Features:**

- Glass Passivated Chip Junctions
- Surge Overload Rating: 50A (Peak)
- Ideal for Printed Circuit Board
- High Temperature Soldering Guaranteed: +285°C/10 seconds at 5 lbs., (2.3kg) tension

**Maximum Ratings and Electrical Characteristics:** ( $T_A = +25^\circ\text{C}$  unless otherwise specified, 60Hz, Resistive or Inductive Load.)

|   |                    |
|---|--------------------|
| Maximum Recurrent Peak Reverse Voltage, $V_{RRM}$   |                    |
| NTE5332 .....   | 600V               |
| NTE5334 .....   | 1000V              |
| Maximum RMS, $V_{RMS}$  |                    |
| NTE5332 .....   | 420V               |
| NTE5334 .....   | 700V               |
| Maximum DC Blocking Voltage, $V_{DC}$   |                    |
| NTE5332 .....   | 600V               |
| NTE5334 .....   | 1000V              |
| Maximum Average Forward Output Rectified Current ( $T_A = +40^\circ\text{C}$ ), $I_{O(AV)}$ | 1A                 |
| Peak Forward Surge Current (Single Sine-Wave Superimposed on Rated Load), $I_{FSM}$         | 50A                |
| Rating for Fusing ( $t < 8.35\text{ms}$ ), $I^2t$   | 10A <sup>2</sup> s |
| Maximum Instantaneous Forward Voltage Drop (Per element at 1A), $V_F$                       | 1.2V               |
| Maximum Reverse Current at Rated DC Blocking Voltage Per Element, $I_R$                     |                    |
| $T_A = +25^\circ\text{C}$ .....   | 10 $\mu\text{A}$   |
| $T_A = +125^\circ\text{C}$ .....  | 500 $\mu\text{A}$  |
| Typical Junction Capacitance Per Element (Note 1), $C_J$                                    | 25pf               |
| Typical thermal Resistance (Note 2), $R_{\theta JA}$  | +40°C/W            |
| Operating Junction Temperature Range, $T_J$   | -65° to +150°C     |
| Storage Temperature Range, $T_{stg}$  | -65° to +150°C     |

Note 1. Measured at 1.0MHz and applied reverse voltage of 4.0 Volts.

Note 2. Thermal Resistance from Junction to Ambient mounted on P.C. Board with 0.5" x 0.5" (13mm x 13mm) Copper Pads.

